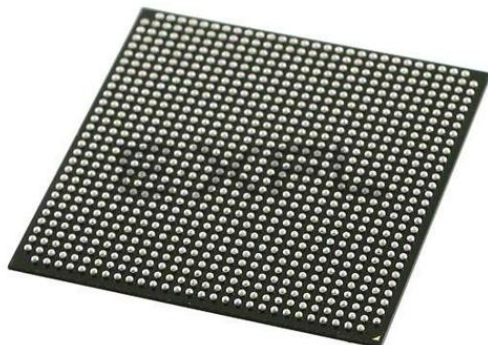




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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details

Product Status	Obsolete
Number of LABs/CLBs	3537
Number of Logic Elements/Cells	75000
Total RAM Bits	8666112
Number of I/O	416
Number of Gates	-
Voltage - Supply	1.07V ~ 1.13V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	896-BBGA, FCBGA
Supplier Device Package	896-FBGA (31x31)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5agxba1d4f31c4n

Caution: Conditions outside the range listed in the following table may cause permanent damage to the device. Additionally, device operation at the absolute maximum ratings for extended periods of time may have adverse effects on the device.

Table 1-1: Absolute Maximum Ratings for Arria V Devices

Symbol	Description	Minimum	Maximum	Unit
V _{CC}	Core voltage power supply	–0.50	1.43	V
V _{CCP}	Periphery circuitry, PCIe [®] hardIP block, and transceiver physical coding sublayer (PCS) power supply	–0.50	1.43	V
V _{CCPGM}	Configuration pins power supply	–0.50	3.90	V
V _{CC_AUX}	Auxiliary supply	–0.50	3.25	V
V _{CCBAT}	Battery back-up power supply for design security volatile key register	–0.50	3.90	V
V _{CCPD}	I/O pre-driver power supply	–0.50	3.90	V
V _{CCIO}	I/O power supply	–0.50	3.90	V
V _{CCD_FPLL}	Phase-locked loop (PLL) digital power supply	–0.50	1.80	V
V _{CCA_FPLL}	PLL analog power supply	–0.50	3.25	V
V _{CCA_GXB}	Transceiver high voltage power	–0.50	3.25	V
V _{CCH_GXB}	Transmitter output buffer power	–0.50	1.80	V
V _{CCR_GXB}	Receiver power	–0.50	1.50	V
V _{CCT_GXB}	Transmitter power	–0.50	1.50	V
V _{CCL_GXB}	Transceiver clock network power	–0.50	1.50	V
V _I	DC input voltage	–0.50	3.80	V
V _{CC_HPS}	HPS core voltage and periphery circuitry power supply	–0.50	1.43	V
V _{CCPD_HPS}	HPS I/O pre-driver power supply	–0.50	3.90	V
V _{CCIO_HPS}	HPS I/O power supply	–0.50	3.90	V
V _{CCRSTCLK_HPS}	HPS reset and clock input pins power supply	–0.50	3.90	V

Symbol	Description	Minimum	Maximum	Unit
V _{CCPLL_HPS}	HPS PLL analog power supply	–0.50	3.25	V
V _{CC_AUX_SHARED}	HPS auxiliary power supply	–0.50	3.25	V
I _{OUT}	DC output current per pin	–25	40	mA
T _J	Operating junction temperature	–55	125	°C
T _{STG}	Storage temperature (no bias)	–65	150	°C

Maximum Allowed Overshoot and Undershoot Voltage

During transitions, input signals may overshoot to the voltage listed in the following table and undershoot to –2.0 V for input currents less than 100 mA and periods shorter than 20 ns.

The maximum allowed overshoot duration is specified as a percentage of high time over the lifetime of the device. A DC signal is equivalent to 100% duty cycle.

For example, a signal that overshoots to 4.00 V can only be at 4.00 V for ~15% over the lifetime of the device; for a device lifetime of 10 years, this amounts to 1.5 years.

Table 1-2: Maximum Allowed Overshoot During Transitions for Arria V Devices

This table lists the maximum allowed input overshoot voltage and the duration of the overshoot voltage as a percentage of device lifetime.

Transceiver Power Supply Operating Conditions

Table 1-4: Transceiver Power Supply Operating Conditions for Arria V Devices

Symbol	Description	Minimum ⁽⁵⁾	Typical	Maximum ⁽⁵⁾	Unit
V _{CCA_GXBL}	Transceiver high voltage power (left side)	2.375	2.500	2.625	V
V _{CCA_GXBR}	Transceiver high voltage power (right side)				
V _{CCR_GXBL}	GX and SX speed grades—receiver power (left side)	1.08/1.12	1.1/1.15 ⁽⁶⁾	1.14/1.18	V
V _{CCR_GXBR}	GX and SX speed grades—receiver power (right side)				
V _{CCR_GXBL}	GT and ST speed grades—receiver power (left side)	1.17	1.20	1.23	V
V _{CCR_GXBR}	GT and ST speed grades—receiver power (right side)				
V _{CCT_GXBL}	GX and SX speed grades—transmitter power (left side)	1.08/1.12	1.1/1.15 ⁽⁶⁾	1.14/1.18	V
V _{CCT_GXBR}	GX and SX speed grades—transmitter power (right side)				
V _{CCT_GXBL}	GT and ST speed grades—transmitter power (left side)	1.17	1.20	1.23	V
V _{CCT_GXBR}	GT and ST speed grades—transmitter power (right side)				
V _{CCH_GXBL}	Transmitter output buffer power (left side)	1.425	1.500	1.575	V
V _{CCH_GXBR}	Transmitter output buffer power (right side)				

⁽⁵⁾ The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

⁽⁶⁾ For data rate ≤ 3.2 Gbps, connect V_{CCR_GXBL/R}, V_{CCT_GXBL/R}, or V_{CCL_GXBL/R} to either 1.1-V or 1.15-V power supply. For data rate > 3.2 Gbps, connect V_{CCR_GXBL/R}, V_{CCT_GXBL/R}, or V_{CCL_GXBL/R} to a 1.15-V power supply. For details, refer to the Arria V GT, GX, ST, and SX Device Family Pin Connection Guidelines.

Symbol	Description	V _{CCIO} (V)	Value	Unit
dR/dT	OCT variation with temperature without recalibration	3.0	0.189	%/ ^o C
		2.5	0.208	
		1.8	0.266	
		1.5	0.273	
		1.35	0.200	
		1.25	0.200	
		1.2	0.317	

Pin Capacitance

Table 1-11: Pin Capacitance for Arria V Devices

Symbol	Description	Maximum	Unit
C _{IOTB}	Input capacitance on top/bottom I/O pins	6	pF
C _{IOLR}	Input capacitance on left/right I/O pins	6	pF
C _{OUTFB}	Input capacitance on dual-purpose clock output/feedback pins	6	pF
C _{IOVREF}	Input capacitance on V _{REF} pins	48	pF

Hot Socketing

Table 1-12: Hot Socketing Specifications for Arria V Devices

Symbol	Description	Maximum	Unit
I _{IOPIN} (DC)	DC current per I/O pin	300	μA
I _{IOPIN} (AC)	AC current per I/O pin	8 ⁽¹⁰⁾	mA
I _{XCVR-TX} (DC)	DC current per transceiver transmitter (TX) pin	100	mA

Symbol/Description	Condition	Transceiver Speed Grade 4			Transceiver Speed Grade 6			Unit
		Min	Typ	Max	Min	Typ	Max	
Spread-spectrum modulating clock frequency	PCI Express® (PCIe)	30	—	33	30	—	33	kHz
Spread-spectrum downspread	PCIe	—	0 to -0.5%	—	—	0 to -0.5%	—	—
On-chip termination resistors	—	—	100	—	—	100	—	Ω
V _{ICM} (AC coupled)	—	—	1.1/1.15 ⁽²⁶⁾	—	—	1.1/1.15 ⁽²⁶⁾	—	V
V _{ICM} (DC coupled)	HCSL I/O standard for the PCIe reference clock	250	—	550	250	—	550	mV
Transmitter REFCLK phase noise ⁽²⁷⁾	10 Hz	—	—	-50	—	—	-50	dBc/Hz
	100 Hz	—	—	-80	—	—	-80	dBc/Hz
	1 KHz	—	—	-110	—	—	-110	dBc/Hz
	10 KHz	—	—	-120	—	—	-120	dBc/Hz
	100 KHz	—	—	-120	—	—	-120	dBc/Hz
	≥1 MHz	—	—	-130	—	—	-130	dBc/Hz
R _{REF}	—	—	2000 ±1%	—	—	2000 ±1%	—	Ω

⁽²⁶⁾ For data rate ≤3.2 Gbps, connect V_{CCR_GXBL/R} to either 1.1-V or 1.15-V power supply. For data rate >3.2 Gbps, connect V_{CCR_GXBL/R} to a 1.15-V power supply. For details, refer to the Arria V GT, GX, ST, and SX Device Family Pin Connection Guidelines.

⁽²⁷⁾ The transmitter REFCLK phase jitter is 30 ps p-p at bit error rate (BER) 10⁻¹².

FPP Configuration Timing when DCLK-to-DATA[] >1

Table 1-67: FPP Timing Parameters When DCLK-to-DATA[] Ratio is >1 for Arria V Devices

Use these timing parameters when you use the decompression and design security features.

Symbol	Parameter	Minimum	Maximum	Unit
t_{CF2CD}	nCONFIG low to CONF_DONE low	—	600	ns
t_{CF2ST0}	nCONFIG low to nSTATUS low	—	600	ns
t_{CFG}	nCONFIG low pulse width	2	—	μ s
t_{STATUS}	nSTATUS low pulse width	268	1506 ⁽⁹⁸⁾	μ s
t_{CF2ST1}	nCONFIG high to nSTATUS high	—	1506 ⁽⁹⁹⁾	μ s
$t_{CF2CK}^{(100)}$	nCONFIG high to first rising edge on DCLK	1506	—	μ s
$t_{ST2CK}^{(100)}$	nSTATUS high to first rising edge of DCLK	2	—	μ s
t_{DSU}	DATA[] setup time before rising edge on DCLK	5.5	—	ns
t_{DH}	DATA[] hold time after rising edge on DCLK	$N - 1/f_{DCLK}^{(101)}$	—	s
t_{CH}	DCLK high time	$0.45 \times 1/f_{MAX}$	—	s
t_{CL}	DCLK low time	$0.45 \times 1/f_{MAX}$	—	s
t_{CLK}	DCLK period	$1/f_{MAX}$	—	s
f_{MAX}	DCLK frequency (FPP $\times 8/ \times 16$)	—	125	MHz
t_R	Input rise time	—	40	ns
t_F	Input fall time	—	40	ns
t_{CD2UM}	CONF_DONE high to user mode ⁽¹⁰²⁾	175	437	μ s

⁽⁹⁸⁾ This value can be obtained if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.

⁽⁹⁹⁾ This value can be obtained if you do not delay configuration by externally holding nSTATUS low.

⁽¹⁰⁰⁾ If nSTATUS is monitored, follow the t_{ST2CK} specification. If nSTATUS is not monitored, follow the t_{CF2CK} specification.

⁽¹⁰¹⁾ N is the DCLK-to-DATA[] ratio and f_{DCLK} is the DCLK frequency of the system.

⁽¹⁰²⁾ The minimum and maximum numbers apply only if you chose the internal oscillator as the clock source for initializing the device.

Symbol	Parameter	Minimum	Maximum	Unit
$t_{CF2CK}^{(105)}$	nCONFIG high to first rising edge on DCLK	1506	—	μ s
$t_{ST2CK}^{(105)}$	nSTATUS high to first rising edge of DCLK	2	—	μ s
t_{DSU}	DATA[] setup time before rising edge on DCLK	5.5	—	ns
t_{DH}	DATA[] hold time after rising edge on DCLK	0	—	ns
t_{CH}	DCLK high time	$0.45 \times 1/f_{MAX}$	—	s
t_{CL}	DCLK low time	$0.45 \times 1/f_{MAX}$	—	s
t_{CLK}	DCLK period	$1/f_{MAX}$	—	s
f_{MAX}	DCLK frequency	—	125	MHz
t_{CD2UM}	CONF_DONE high to user mode ⁽¹⁰⁶⁾	175	437	μ s
t_{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	—	—
t_{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	$t_{CD2CU} + (T_{init} \times \text{CLKUSR period})$	—	—
T_{init}	Number of clock cycles required for device initialization	8,576	—	Cycles

Related Information**PS Configuration Timing**

Provides the PS configuration timing waveform.

⁽¹⁰⁵⁾ If nSTATUS is monitored, follow the t_{ST2CK} specification. If nSTATUS is not monitored, follow the t_{CF2CK} specification.

⁽¹⁰⁶⁾ The minimum and maximum numbers apply only if you chose the internal oscillator as the clock source for initializing the device.

Term	Definition
V_{OX}	Output differential cross point voltage
W	High-speed I/O block—Clock boost factor

Document Revision History

Date	Version	Changes
December 2016	2016.12.09	- Updated V_{ICM} (AC coupled) specifications in Receiver Specifications for Arria V GX and SX Devices table. - Added maximum specification for T_d in Management Data Input/Output (MDIO) Timing Requirements for Arria V Devices table. - Updated T_{init} specifications in the following tables: - FPP Timing Parameters When DCLK-to-DATA[] Ratio is 1 for Arria V Devices - FPP Timing Parameters When DCLK-to-DATA[] Ratio is >1 for Arria V Devices - AS Timing Parameters for AS $\times 1$ and $\times 4$ Configurations in Arria V Devices - PS Timing Parameters for Arria V Devices
June 2016	2016.06.10	- Changed pin capacitance to maximum values. - Updated SPI Master Timing Requirements for Arria V Devices table. - Added T_{su} and T_h specifications. - Removed T_{dinmax} specifications. - Updated SPI Master Timing Diagram. - Updated T_{clk} spec from maximum to minimum in I²C Timing Requirements for Arria V Devices table.

Date	Version	Changes
June 2012	2.0	• Updated for the Quartus II software v12.0 release: • Restructured document. • Updated “Supply Current and Power Consumption” section. • Updated Table 20, Table 21, Table 24, Table 25, Table 26, Table 35, Table 39, Table 43, and Table 52. • Added Table 22, Table 23, and Table 33. • Added Figure 1–1 and Figure 1–2. • Added “Initialization” and “Configuration Files” sections.
February 2012	1.3	• Updated Table 2–1. • Updated Transceiver-FPGA Fabric Interface rows in Table 2–20. • Updated V_{CCP} description.
December 2011	1.2	Updated Table 2–1 and Table 2–3.
November 2011	1.1	• Updated Table 2–1, Table 2–19, Table 2–26, and Table 2–36. • Added Table 2–5. • Added Figure 2–4.
August 2011	1.0	Initial release.

Lower number refers to faster speed grade.

L = Low power devices.

Transceiver Speed Grade	Core Speed Grade			
	C3	C4	I3L	I4
2	Yes	—	Yes	—
3	—	Yes	—	Yes

Absolute Maximum Ratings

Absolute maximum ratings define the maximum operating conditions for Arria V GZ devices. The values are based on experiments conducted with the devices and theoretical modeling of breakdown and damage mechanisms. The functional operation of the device is not implied for these conditions.

Caution: Conditions other than those listed in the following table may cause permanent damage to the device. Additionally, device operation at the absolute maximum ratings for extended periods of time may have adverse effects on the device.

Table 2-2: Absolute Maximum Ratings for Arria V GZ Devices

Symbol	Description	Minimum	Maximum	Unit
V _{CC}	Power supply for core voltage and periphery circuitry	−0.5	1.35	V
V _{CCPT}	Power supply for programmable power technology	−0.5	1.8	V
V _{CCPGM}	Power supply for configuration pins	−0.5	3.9	V
V _{CC_AUX}	Auxiliary supply for the programmable power technology	−0.5	3.4	V
V _{CCBAT}	Battery back-up power supply for design security volatile key register	−0.5	3.9	V
V _{CCPD}	I/O pre-driver power supply	−0.5	3.9	V
V _{CCIO}	I/O power supply	−0.5	3.9	V
V _{CCD_FPLL}	PLL digital power supply	−0.5	1.8	V
V _{CCA_FPLL}	PLL analog power supply	−0.5	3.4	V

I/O Standard	V_{CCIO} (V)			V_{REF} (V)			V_{TT} (V)		
	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max
SSTL-135 Class I, II	1.283	1.35	1.418	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$
SSTL-125 Class I, II	1.19	1.25	1.26	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$
SSTL-12 Class I, II	1.14	1.20	1.26	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$
HSTL-18 Class I, II	1.71	1.8	1.89	0.85	0.9	0.95	—	$V_{CCIO}/2$	—
HSTL-15 Class I, II	1.425	1.5	1.575	0.68	0.75	0.9	—	$V_{CCIO}/2$	—
HSTL-12 Class I, II	1.14	1.2	1.26	$0.47 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.53 \times V_{CCIO}$	—	$V_{CCIO}/2$	—
HSUL-12	1.14	1.2	1.3	$0.49 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.51 \times V_{CCIO}$	—	—	—

Table 2-18: Single-Ended SSTL, HSTL, and HSUL I/O Standards Signal Specifications for Arria V GZ Devices

I/O Standard	$V_{IL(DC)}$ (V)		$V_{IH(DC)}$ (V)		$V_{IL(AC)}$ (V)	$V_{IH(AC)}$ (V)	V_{OL} (V)	V_{OH} (V)	I_{ol} (mA)	I_{oh} (mA)
	Min	Max	Min	Max	Max	Min	Max	Min		
SSTL-2 Class I	-0.3	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$V_{CCIO} + 0.3$	$V_{REF} - 0.31$	$V_{REF} + 0.31$	$V_{TT} - 0.608$	$V_{TT} + 0.608$	8.1	-8.1
SSTL-2 Class II	-0.3	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$V_{CCIO} + 0.3$	$V_{REF} - 0.31$	$V_{REF} + 0.31$	$V_{TT} - 0.81$	$V_{TT} + 0.81$	16.2	-16.2
SSTL-18 Class I	-0.3	$V_{REF} - 0.125$	$V_{REF} + 0.125$	$V_{CCIO} + 0.3$	$V_{REF} - 0.25$	$V_{REF} + 0.25$	$V_{TT} - 0.603$	$V_{TT} + 0.603$	6.7	-6.7

I/O Standard	$V_{IL(DC)} (V)$		$V_{IH(DC)} (V)$		$V_{IL(AC)} (V)$	$V_{IH(AC)} (V)$	$V_{OL} (V)$	$V_{OH} (V)$	$I_{ol} (mA)$	$I_{oh} (mA)$
	Min	Max	Min	Max	Max	Min	Max	Min		
SSTL-18 Class II	-0.3	$V_{REF} - 0.125$	$V_{REF} + 0.125$	$V_{CCIO} + 0.3$	$V_{REF} - 0.25$	$V_{REF} + 0.25$	0.28	$V_{CCIO} - 0.28$	13.4	-13.4
SSTL-15 Class I	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.175$	$V_{REF} + 0.175$	$0.2 \times V_{CCIO}$	$0.8 \times V_{CCIO}$	8	-8
SSTL-15 Class II	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.175$	$V_{REF} + 0.175$	$0.2 \times V_{CCIO}$	$0.8 \times V_{CCIO}$	16	-16
SSTL-135 Class I, II	—	$V_{REF} - 0.09$	$V_{REF} + 0.09$	—	$V_{REF} - 0.16$	$V_{REF} + 0.16$	$0.2 * V_{CCIO}$	$0.8 * V_{CCIO}$	—	—
SSTL-125 Class I, II	—	$V_{REF} - 0.85$	$V_{REF} + 0.85$	—	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$0.2 * V_{CCIO}$	$0.8 * V_{CCIO}$	—	—
SSTL-12 Class I, II	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$0.2 * V_{CCIO}$	$0.8 * V_{CCIO}$	—	—
HSTL-18 Class I	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.2$	$V_{REF} + 0.2$	0.4	$V_{CCIO} - 0.4$	8	-8
HSTL-18 Class II	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.2$	$V_{REF} + 0.2$	0.4	$V_{CCIO} - 0.4$	16	-16
HSTL-15 Class I	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.2$	$V_{REF} + 0.2$	0.4	$V_{CCIO} - 0.4$	8	-8
HSTL-15 Class II	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.2$	$V_{REF} + 0.2$	0.4	$V_{CCIO} - 0.4$	16	-16
HSTL-12 Class I	-0.15	$V_{REF} - 0.08$	$V_{REF} + 0.08$	$V_{CCIO} + 0.15$	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$0.25 \times V_{CCIO}$	$0.75 \times V_{CCIO}$	8	-8
HSTL-12 Class II	-0.15	$V_{REF} - 0.08$	$V_{REF} + 0.08$	$V_{CCIO} + 0.15$	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$0.25 \times V_{CCIO}$	$0.75 \times V_{CCIO}$	16	-16
HSUL-12	—	$V_{REF} - 0.13$	$V_{REF} + 0.13$	—	$V_{REF} - 0.22$	$V_{REF} + 0.22$	$0.1 \times V_{CCIO}$	$0.9 \times V_{CCIO}$	—	—

Memory	Mode	Resources Used		Performance				Unit
		ALUTs	Memory	C3	C4	I3L	I4	
M20K Block	Single-port, all supported widths	0	1	650	550	500	450	MHz
	Simple dual-port, all supported widths	0	1	650	550	500	450	MHz
	Simple dual-port with the read-during-write option set to Old Data , all supported widths	0	1	455	400	455	400	MHz
	Simple dual-port with ECC enabled, 512×32	0	1	400	350	400	350	MHz
	Simple dual-port with ECC and optional pipeline registers enabled, 512×32	0	1	500	450	500	450	MHz
	True dual port, all supported widths	0	1	650	550	500	450	MHz
	ROM, all supported widths	0	1	650	550	500	450	MHz

Temperature Sensing Diode Specifications

Table 2-37: Internal Temperature Sensing Diode Specification

Temperature Range	Accuracy	Offset Calibrated Option	Sampling Rate	Conversion Time	Resolution	Minimum Resolution with no Missing Codes
-40°C to 100°C	±8°C	No	1 MHz, 500 kHz	< 100 ms	8 bits	8 bits

Table 2-38: External Temperature Sensing Diode Specifications for Arria V GZ Devices

Description	Min	Typ	Max	Unit
I_{bias} , diode source current	8	—	200	μA
V_{bias} , voltage across diode	0.3	—	0.9	V
Series resistance	—	—	< 1	Ω

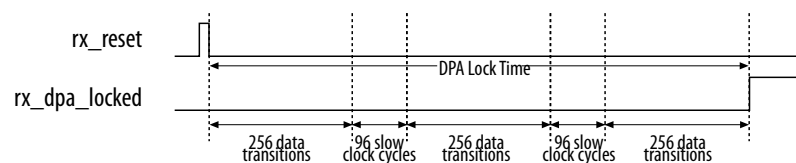
DPA Mode High-Speed I/O Specifications

Table 2-42: High-Speed I/O Specifications for Arria V GZ Devices

When J = 3 to 10, use the serializer/deserializer (SERDES) block.

When J = 1 or 2, bypass the SERDES block.

Symbol	Conditions	C3, I3L			C4, I4			Unit
		Min	Typ	Max	Min	Typ	Max	
DPA run length	—	—	—	10000	—	—	10000	UI

Figure 2-3: DPA Lock Time Specification with DPA PLL Calibration Enabled**Table 2-43: DPA Lock Time Specifications for Arria V GZ Devices**

The DPA lock time is for one channel.

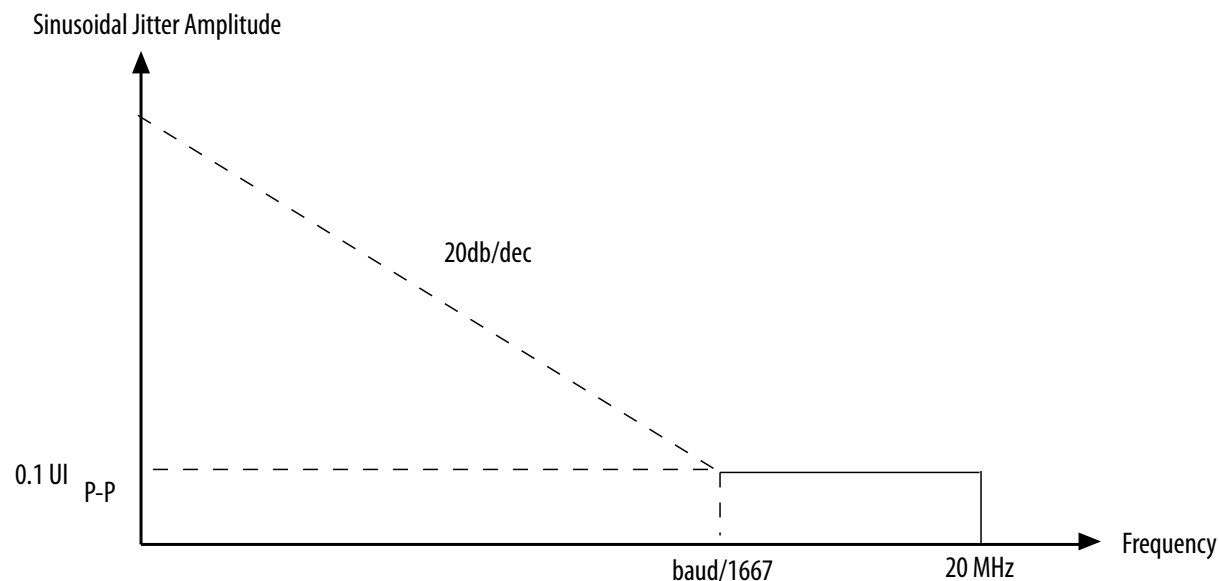
One data transition is defined as a 0-to-1 or 1-to-0 transition.

The DPA lock time stated in this table applies to both commercial and industrial grade.

Standard	Training Pattern	Number of Data Transitions in One Repetition of the Training Pattern	Number of Repetitions per 256 Data Transitions ⁽²⁰¹⁾	Maximum
SPI-4	00000000001111111111	2	128	640 data transitions

⁽²⁰¹⁾ This is the number of repetitions for the stated training pattern to achieve the 256 data transitions.

Figure 2-5: LVDS Soft-CDR/DPA Sinusoidal Jitter Tolerance Specification for a Data Rate < 1.25 Gbps



Non DPA Mode High-Speed I/O Specifications

Table 2-46: High-Speed I/O Specifications for Arria V GZ Devices

When J = 3 to 10, use the serializer/deserializer (SERDES) block.

When J = 1 or 2, bypass the SERDES block.

Symbol	Conditions	C3, I3L			C4, I4			Unit
		Min	Typ	Max	Min	Typ	Max	
Sampling Window	—	—	—	300	—	—	300	ps

Table 2-55: DCLK-to-DATA[] Ratio for Arria V GZ Devices

Depending on the DCLK-to-DATA[] ratio, the host must send a DCLK frequency that is r times the data rate in bytes per second (Bps), or words per second (Wps). For example, in FPP ×16 when the DCLK-to-DATA[] ratio is 2, the DCLK frequency must be 2 times the data rate in Wps. Arria V GZ devices use the additional clock cycles to decrypt and decompress the configuration data.

Configuration Scheme	Decompression	Design Security	DCLK-to-DATA[] Ratio
FPP ×8	Disabled	Disabled	1
	Disabled	Enabled	1
	Enabled	Disabled	2
	Enabled	Enabled	2
FPP ×16	Disabled	Disabled	1
	Disabled	Enabled	2
	Enabled	Disabled	4
	Enabled	Enabled	4
FPP ×32	Disabled	Disabled	1
	Disabled	Enabled	4
	Enabled	Disabled	8
	Enabled	Enabled	8

Programmable IOE Delay

Table 2-66: IOE Programmable Delay for Arria V GZ Devices

Parameter ⁽²²⁸⁾	Available Settings	Min Offset ⁽²²⁹⁾	Fast Model		Slow Model				Unit
			Industrial	Commercial	C3	C4	I3L	I4	
D1	64	0	0.464	0.493	0.924	1.011	0.921	1.006	ns
D2	32	0	0.230	0.244	0.459	0.503	0.456	0.500	ns
D3	8	0	1.587	1.699	2.992	3.192	3.047	3.257	ns
D4	64	0	0.464	0.492	0.924	1.011	0.920	1.006	ns
D5	64	0	0.464	0.493	0.924	1.011	0.921	1.006	ns
D6	32	0	0.229	0.244	0.458	0.503	0.456	0.499	ns

Programmable Output Buffer Delay

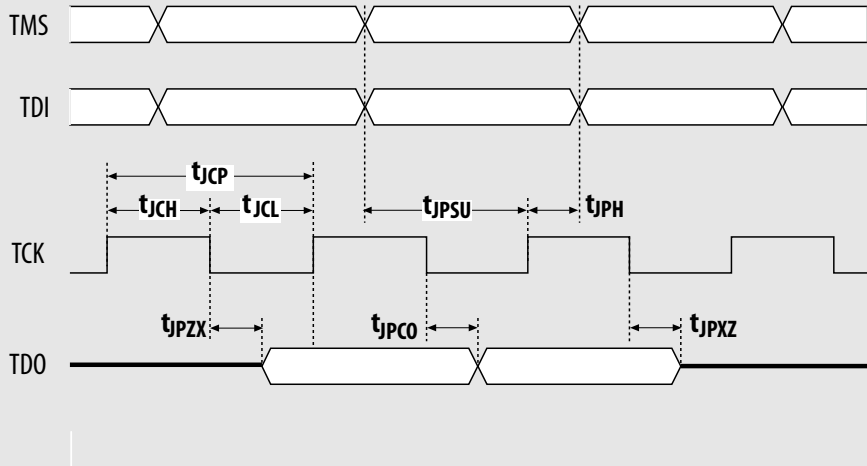
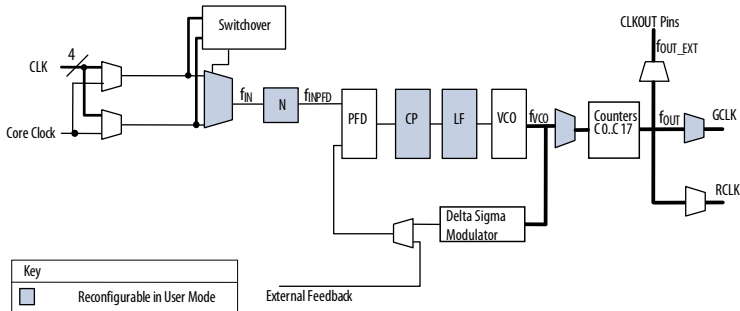
Table 2-67: Programmable Output Buffer Delay for Arria V GZ Devices

You can set the programmable output buffer delay in the Quartus II software by setting the **Output Buffer Delay Control** assignment to either positive, negative, or both edges, with the specific values stated here (in ps) for the **Output Buffer Delay** assignment.

Symbol	Parameter	Typical	Unit
D _{OUTBUF}	Rising and/or falling edge delay	0 (default)	ps
		50	ps
		100	ps
		150	ps

⁽²²⁸⁾ You can set this value in the Quartus II software by selecting **D1**, **D2**, **D3**, **D4**, **D5**, and **D6** in the **Assignment Name** column of **Assignment Editor**.

⁽²²⁹⁾ Minimum offset does not include the intrinsic delay.

Term	Definition
JTAG Timing Specifications	JTAG Timing Specifications:  The diagram illustrates the timing relationships between JTAG signals. TMS and TDI are shown as high-impedance tri-state buffers. TCK is a clock signal with parameters t_{JCH} (setup), t_{JCL} (hold), t_{JCP} (pulse width), t_{JPSU} (setup), t_{JPH} (hold), and t_{JPXZ} (pulse width). TDO is a data signal with parameters t_{JPZX} (setup), t_{JPCO} (hold), and t_{JPXZ} (pulse width).
PLL Specifications	Diagram of PLL Specifications  The diagram shows the internal structure of a PLL. A Core Clock (CLK) is divided by 4 and fed into a Switchover block. The Switchover block outputs a signal to a PFD (Phase-Frequency Detector) block, which is also fed by a feedback signal from a Delta Sigma Modulator. The PFD output goes through a CP (Charge Pump) block, then an LF (Loop Filter) block, and finally a VCO (Voltage-Controlled Oscillator) block. The VCO output is fed into a Counters block (CO, C 17), which outputs f_{OUT} to CLKOUT Pins. The Counters block also outputs f_{OUT} to GCLK and RCLK. A Delta Sigma Modulator block is connected to the VCO output and the Counters block. A Key indicates that blue-shaded blocks are Reconfigurable in User Mode. A Note states: 1. Core Clock can only be fed by dedicated clock input pins or PLL outputs.

Date	Version	Changes
June 2016	2016.06.20	• Changed column heading from "Value" to "Maximum" in the "Pin Capacitance for Arria V GZ Devices" table. • Changed the minimum supported data rate range values from "1000" to "2000" in the "ATX PLL Specifications for Arria V GZ Devices" table. • Added the supported data rates for the following output standards using true LVDS output buffer types in the "High-Speed Clock Specifications for Arria V GZ Devices" table: • True RSDS output standard: data rates of up to 230 Mbps • True mini-LVDS output standard: data rates of up to 340 Mbps
December 2015	2015.12.16	• Removed the CDR ppm tolerance specification from the "Receiver Specifications for Arria V GZ Devices" table. • Removed transmitter rise and fall time specifications from the "Transmitter Specifications for Arria V GZ Devices" table. • Changed the .rbf sizes in the "Uncompressed .rbf Sizes for Arria V GZ Devices" table. • Added a footnote to the "Transmitter High-Speed I/O Specifications for Arria V GZ Devices" table.
June 2015	2015.06.16	• Changed the conditions for the reference clock rise and fall time and added a note to the condition in the "Reference Clock Specifications for Arria V GZ Devices" table. • Added a note to the "Minimum differential eye opening at receiver serial input pins" specification in the "Receiver Specifications for Arria V GZ Devices" table.
January 2015	2015.01.30	• Added 240-Ω to the "OCT Calibration Accuracy Specifications for Arria V GZ Devices" table. • Changed the CDR PPM tolerance spec in the "Receiver Specifications for Arria V GZ Devices" table. • Added additional max data rate for fPLL in the "Fractional PLL Specifications for Arria V GZ Devices" table.

Date	Version	Changes
July 2014	3.8	- Updated Table 21. - Updated Table 22 V_{OCM} (DC Coupled) condition. - Updated the DCLK note to Figure 6, Figure 7, and Figure 9. - Added note to Table 5 and Table 6. - Added the DCLK specification to Table 50. - Added note to Table 51. - Updated the list of parameters in Table 53.
February 2014	3.7	Updated Table 28.
December 2013	3.6	- Updated Table 2, Table 13, Table 18, Table 19, Table 22, Table 30, Table 33, Table 37, Table 38, Table 45, Table 46, Table 47, Table 56, Table 49. - Updated “PLL Specifications”.
August 2013	3.5	Updated Table 28.
August 2013	3.4	- Removed Preliminary tags for Table 2, Table 4, Table 5, Table 14, Table 27, Table 28, Table 29, Table 31, Table 32, Table 43, Table 45, Table 46, Table 47, Table 48, Table 49, Table 50, and Table 54. - Updated Table 2 and Table 28.
June 2013	3.3	Updated Table 23, Table 28, Table 51, and Table 55.
May 2013	3.2	- Added Table 23. - Updated Table 5, Table 22, Table 26, and Table 57. - Updated Figure 6, Figure 7, Figure 8, and Figure 9.
March 2013	3.1	- Updated Table 2, Table 6, Table 7, Table 8, Table 19, Table 22, Table 26, Table 29, Table 52. - Updated “Maximum Allowed Overshoot and Undershoot Voltage”.
December 2012	3.0	Initial release.